Amendments to the Claims:

If entered, this listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) An integrated circuit device comprising:

~~a chip carrier with~~ an integrated circuit die fixably attached to a substrate ~~said chip carrier~~ having metal leads; ~~and~~

an encapsulating layer encapsulating said integrated circuit die and substrate; and

an antenna structure molded onto ~~said chip carrier~~ said encapsulating layer and comprising a conductive loaded, resin-based material comprising conductive materials in a base resin host wherein said metal leads are exposed by said encapsulating layer and said antenna structure.

2. (Original) The device according to Claim 1 wherein the ratio, by weight, of said conductive materials to said resin host is between about 0.20 and about 0.40.

3. (Original) The device according to Claim 1 wherein said conductive materials comprise metal powder.

4. (Original) The device according to Claim 3 wherein said metal powder is nickel, copper, or silver.

5. (Original) The device according to Claim 3 wherein said metal powder is a non-conductive material with a metal plating.

6. (Original) The device according to Claim 5 wherein said metal plating is nickel, copper, silver, or alloys thereof.

7. (Original) The device according to Claim 3 wherein said metal powder comprises a diameter of between about 3 μm and about 12 μm.

8. (Original) The device according to Claim 1 wherein said conductive materials comprise non-metal powder.

9. (Original) The device according to Claim 8 wherein said non-metal powder is carbon, graphite, or an amine-based material.

10. (Original) The device according to Claim 1 wherein said conductive materials comprise a combination of metal powder and non-metal powder.

11. (Original) The device according to Claim 1 wherein said conductive materials comprise micron conductive fiber.

12. (Original) The device according to Claim 11 wherein said micron conductive fiber is nickel plated carbon fiber, stainless steel fiber, copper fiber, silver fiber or combinations thereof.

13. (Original) The device according to Claim 11 wherein said micron conductive fiber has a diameter of between about 3 μm and about 12 μm and a length of between about 2 mm and about 14 mm.

14. (Original) The device according to Claim 1 wherein said conductive materials comprise a combination of conductive powder and conductive fiber.

15. (Original) The device according to Claim 1 wherein said antenna structure is electrically connected to said integrated circuit die.

16. (Original) The device according to Claim 15 wherein said electrical connection is by direct contact between said conductive loaded resin-based material and metal interconnects on a substrate within said chip carrier.

17. (Original) The device according to Claim 15 wherein said electrical connection is by direct contact between said conductive loaded resin-based material and external leads of said chip carrier.

18. (Currently Amended) The device according to Claim 1 ~~15~~ wherein said ~~further comprising an~~ encapsulating layer comprises a resin-based material. ~~between said integrated circuit die and said antenna structure.~~

19. (Original) The device according to Claim 15 wherein said electrically contacting is through an opening in said encapsulating layer.

20-72. (Cancelled)